

STRIKE MIL-SPEC RUGGED EMBEDDED COMPUTE SOLUTIONS

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Made in the USA
TAA compliant



SPARROW-STRIKE

Ultra-Small-Form-Factor (USFF) edge processor. Compact and lightweight. Modular chassis and architecture design. NVIDIA Jetson Orin NX (AI at the edge for autonomous/uncrewed) or SMARC x86 Atom CPU (compute at the edge). "Four-Star Best in Show Embedded Computing" at the 2023 AUSA Annual Meeting.

KITE-STRIKE II

Edge AI / computer vision mission computer. NVIDIA Jetson AGX Orin SOM. Sensor ingest and data fusion. Robust IO and system expansion options. Highly SWaP-optimized. Fully modular and configurable. Platinum honoree winner in the 2023 Military and Aerospace Electronics Technology Innovators Awards.



HAWK-STRIKE IV

High-performance, single LRU multi-mission system. Sensor ingest, processing, networking, and storage. Latest Intel Xeon/Core mobile CPU and NVIDIA embedded GPU. Dual high-capacity removable SSDs. Robust expansion and dense IO. Numerous expansion options including multiple video capture or encode channels, ARINC 429, 1553, GPS, CAN, multiport GbE switch or NIC.

RAVEN-STRIKE II

Fully rugged and sealed server-class compute solution. Latest Intel Xeon SP CPU and latest NVIDIA Ampere GPU. PCIe Gen 4.0. High-bandwidth networking and high-capacity storage. Immense configurability and expansion options.



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	Sparrow-Strike	Kite-Strike II	Hawk-Strike IV	Raven-Strike II
Lifecycle Stage	Active Engineering Prototype	Active Pre-Qual Production	Active Pre-Qual Production	Active Pre-Qual Production
Material and Finish	Black anodized machined aluminum	Black anodized machined aluminum	Black anodized machined aluminum	Black anodized machined aluminum
Dimensions (excluding connectors and mounting)	6.7"W x 5.3"D x 3.0"H	Base model: 7.87"W x 8.47"D x 4.23"H; dimensions vary with expansion slices	8.5"W x 13.25"D x 5.1"H	11.7"W x 18.17"D x 7.9"H
Weight	~3.1lbs (config dependent)	~9lbs (config dependent)	~15lbs (config dependent)	~37lbs (config dependent)
Mounting	Base mounted (standard)	Base mounted (standard)	Base mounted (standard)	Base mounted (standard)
CPU	Orin NX: Up to 8-core ARM SMARC: Up to 4-core Intel Atom	NVIDIA Jetson AGX Orin (ARM)	Intel mobile Xeon or Core; standard is Xeon E-2276ML (9th gen)	Intel 3rd gen Xeon SP (up to 205W TDP)
Memory	Orin NX: Up to 16GB SMARC Intel Atom: Up to 16GB	Up to 64GB onboard	Up to 64GB ECC DDR4	Up to 1TB ECC DDR4
GPU	Orin NX: Ampere architecture; 1024 CUDA cores, 32 Tensor cores SMARC: NA	NVIDIA Jetson AGX Orin (Ampere). Up to 2048 CUDA cores, 64 Tensor cores	NVIDIA embedded; options are RTX A1000 or RTX A2000	NVIDIA Ampere (up to 230W TDP)
Storage	Internal (non-removable) m.2 NVME and mSATA storage options	64GB eMMC 5.1 onboard; Removable u.2 NVME and internal m.2 NVME options	Up to (2) removable 2.5" SSD (SATA III) and internal mSATA options	Up to (4) removable 2.5" SSD (SATA III) and internal NVME options
Base System IO	(2) USB 3.0, (2) USB 2.0, (2) GbE, (1) CAN 2.0, (1) serial and (1) RS232 debug, (1) HDMI	(2) USB 3.0, (2) USB 2.0, (5) GbE switched, (4) serial and (1) RS232 debug, (2) CAN, (1) DVI/HDMI; option for (2) 10GbE copper	(2) USB 3.0, (2) USB 2.0, (2) GbE, (2) DVI/HDMI, (5) serial, (1) stereo out/mic in, (1) remote power switch	(2) USB 3.0, (4) USB 2.0, (2) 10GbE LAN, (1) IPMI GbE LAN, (4) GbE LAN, (4) DP++, (1) VGA, (1) RS-232
Expansion	Moderate: (2) m.2 and (1) mPCIe. Options include video capture, GPS, CAN, USB, serial, GbE NIC, GPIO, ARINC-429, 1553, power out. Embedded Function Board (EFB) connector (internal) for Systel-designed IO boards.	Robust: (2) m.2 and (3) mPCIe. Options include video capture and encode, dual 10GbE copper/optical, LTE, GPS, power output, audio, GPIO, ARINC 429, 1553.	Robust: PCIe/104 and (2) mPCIe. Options include video capture and encode, GbE NIC/switch, GPS, CAN, USB, serial, GPIO, ARINC-429, 1553.	Immense: (2) PCIe 4.0 x16, (1) m.2, other. Options include almost any COTS video capture and encode, up to 100GbE fiber, GbE switch, GPS, CAN, USB, serial, GPIO, ARINC-429, 1553, power out, and much more.
Connectors	2M805 for power and IO; HD-BNC for RF	2M805 for power and IO; HD-BNC for RF	MIL-DTL-38999 for power and IO; 2M801 for USB 3.0; HD-BNC for RF	MIL-DTL-38999 for power and IO; rugged circular field for USB 3.0 and 10GbE; rugged RF options available
Rugged Standards	MIL-STD-810H, MIL-STD-1275E, MIL-STD-461G, IP66	MIL-STD-810H, MIL-STD-1275E, MIL-STD-461G, IP66	MIL-STD-810H, MIL-STD-1275E, MIL-STD-461G, IP66	MIL-STD-810H, MIL-STD-1275E, MIL-STD-461G, IP66
Operating Temp	-40C to +55C (config dependent)	-40C to +65C (config dependent)	-40C to +60C (config dependent)	-40C to +55C (config dependent)
Thermal Solution	Passive cooled	Forced air convection (no air over electronics)	Passive cooled	Forced air convection with internal heaters and stir fans
Power	Onboard DC-DC power supply; 12-36VDC (28VDC nominal)	Galvanically isolated DC-DC power supply; 18-36VDC 28VDC nominal	Onboard DC-DC power supply; 18-36VDC (28VDC nominal)	Galvanically isolated DC-DC power supply; 18-36VDC 28VDC nominal
Other	Alternative chassis materials may be available for cost/weight reduction	Add-on modular expansion "slice" options		
Cost	\$	\$\$	\$\$\$	\$\$\$\$

All specifications and information is subject to change. Please contact a Systel sales representative to discuss your configuration.

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